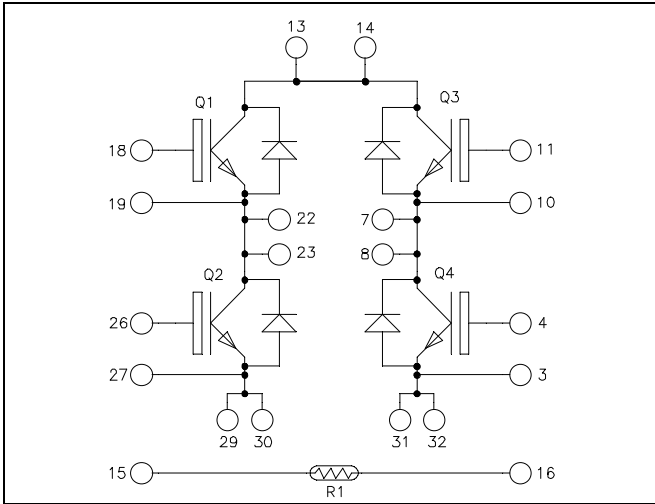


**Full - Bridge
Trench + Field Stop IGBT3
Power Module**

**$V_{CES} = 600V$
 $I_C = 100A^* @ T_c = 80^\circ C$**

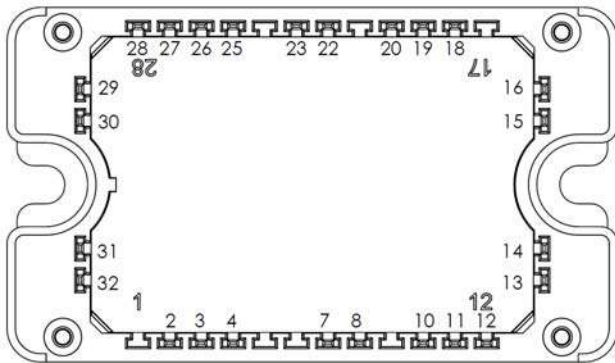


Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- **Trench + Field Stop IGBT3**
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
- Internal thermistor for temperature monitoring



Benefits

- Stable temperature behavior
- Very rugged
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of V_{CEsat}
- Low profile
- Each leg can be easily paralleled to achieve a phase leg of twice the current capability
- RoHS Compliant

All multiple inputs and outputs must be shorted together
 Example: 13/14 ; 29/30 ; 22/23 ...

All ratings @ $T_j = 25^\circ C$ unless otherwise specified

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{CES}	Collector - Emitter Voltage	600	V
I_C	Continuous Collector Current	$T_c = 25^\circ C$	150 *
		$T_c = 80^\circ C$	100 *
I_{CM}	Pulsed Collector Current	$T_c = 25^\circ C$	200
V_{GE}	Gate - Emitter Voltage	± 20	V
P_D	Power Dissipation	$T_c = 25^\circ C$	340
RBSOA	Reverse Bias Safe Operating Area	$T_j = 150^\circ C$	200A @ 550V

* Specification of device but output current must be limited due to size of output pins.

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I _{CES}	Zero Gate Voltage Collector Current	V _{GE} = 0V, V _{CE} = 600V			250	μA
V _{CE(sat)}	Collector Emitter Saturation Voltage	V _{GE} = 15V I _C = 100A		T _j = 25°C 1.5 T _j = 150°C 1.7	1.9	V
V _{GE(th)}	Gate Threshold Voltage	V _{GE} = V _{CE} , I _C = 1.5 mA	5.0	5.8	6.5	V
I _{GES}	Gate – Emitter Leakage Current	V _{GE} = 20V, V _{CE} = 0V			400	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C _{ies}	Input Capacitance	V _{GE} = 0V		6100		pF
C _{oes}	Output Capacitance	V _{CE} = 25V		390		
C _{res}	Reverse Transfer Capacitance	f = 1MHz		190		
T _{d(on)}	Turn-on Delay Time	Inductive Switching (25°C) V _{GE} = ±15V V _{Bus} = 300V I _C = 100A R _G = 3.3Ω		115		ns
T _r	Rise Time			45		
T _{d(off)}	Turn-off Delay Time			225		
T _f	Fall Time			55		
T _{d(on)}	Turn-on Delay Time	Inductive Switching (150°C) V _{GE} = ±15V V _{Bus} = 300V I _C = 100A R _G = 3.3Ω		130		ns
T _r	Rise Time			50		
T _{d(off)}	Turn-off Delay Time			300		
T _f	Fall Time			70		
E _{on}	Turn on Energy	V _{GE} = ±15V V _{Bus} = 300V		0.875		mJ
E _{off}	Turn off Energy	I _C = 100A R _G = 3.3Ω		3.5		mJ
R _{thJC}	Junction to Case Thermal Resistance				0.44	°C/W

Reverse diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V _{RRM}	Peak Repetitive Reverse Voltage				600	V
I _{RM}	Reverse Leakage Current	V _R = 600V			250	μA
I _F	DC Forward Current	T _c = 80°C		100		A
V _F	Diode Forward Voltage	I _F = 100A V _{GE} = 0V		T _j = 25°C 1.6 T _j = 150°C 1.5	2	V
t _{rr}	Reverse Recovery Time	I _F = 100A V _R = 300V di/dt = 2000A/μs		T _j = 25°C 125 T _j = 150°C 220		ns
Q _{rr}	Reverse Recovery Charge			T _j = 25°C 4.7 T _j = 150°C 9.9		μC
E _r	Reverse Recovery Energy			T _j = 25°C 1.1 T _j = 150°C 2.4		mJ
R _{thJC}	Junction to Case Thermal Resistance					0.77

Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C		50		kΩ
ΔR ₂₅ /R ₂₅			5		%
B _{25/85}	T ₂₅ = 298.15 K		3952		K
ΔB/B	T _C = 100°C		4		%

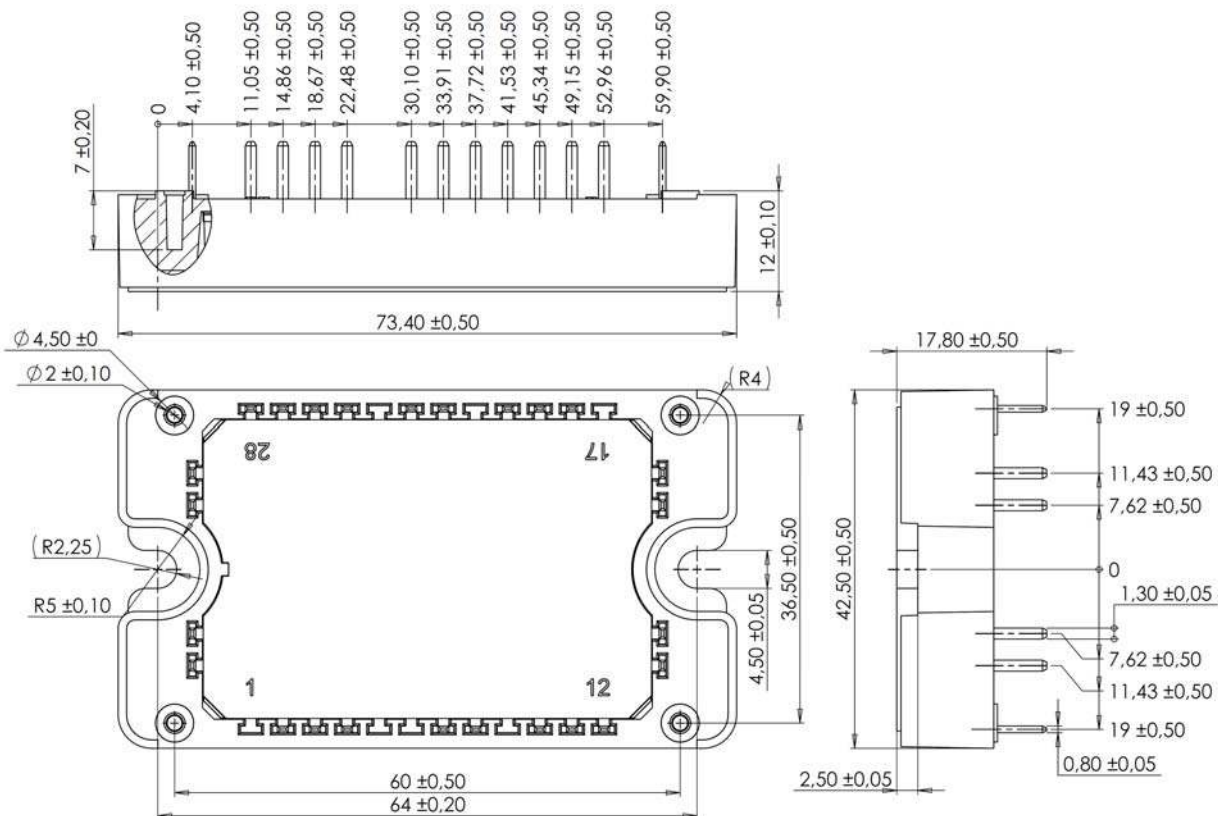
$$R_T = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]}$$

T: Thermistor temperature
 R_T: Thermistor value at T

Thermal and package characteristics

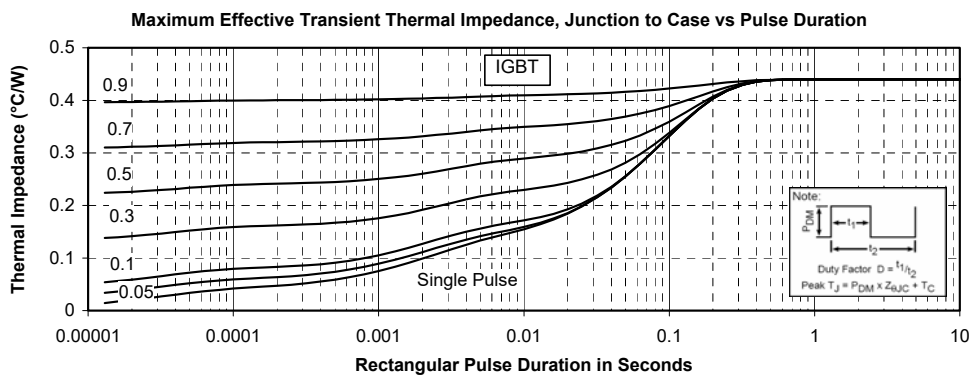
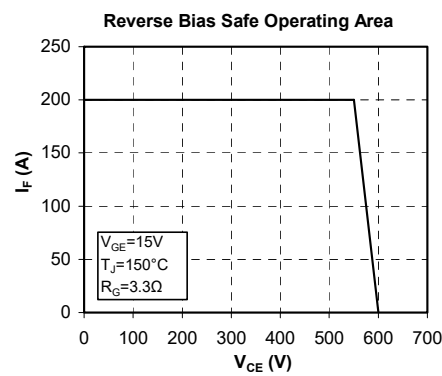
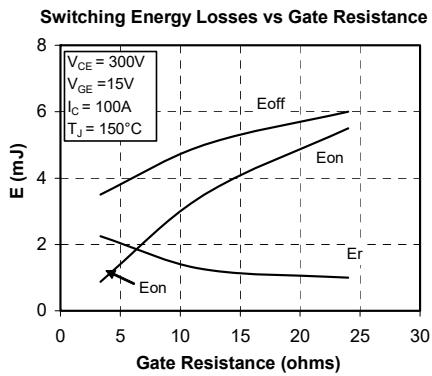
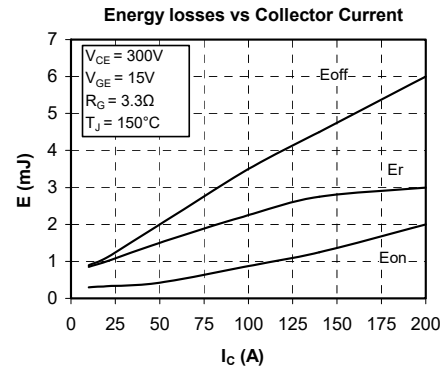
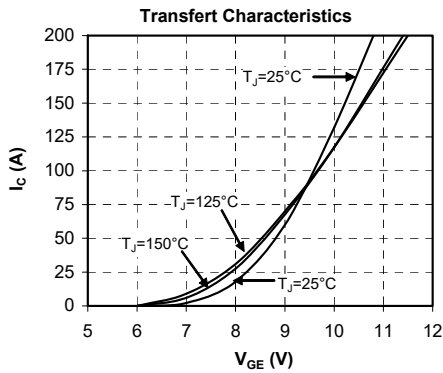
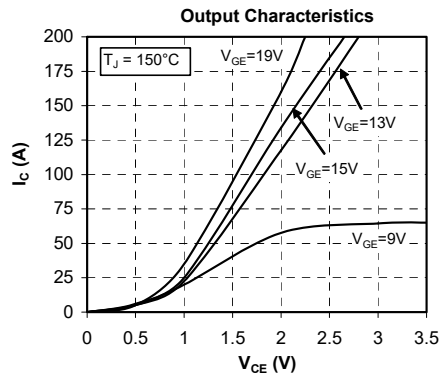
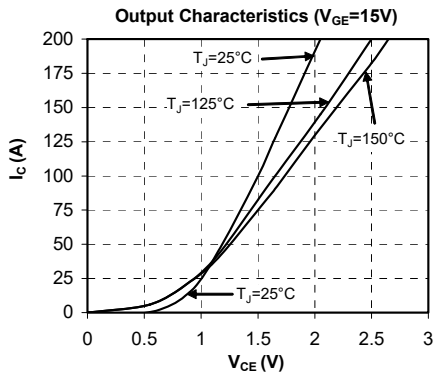
Symbol	Characteristic	Min	Max	Unit		
V _{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz	4000		V		
T _J	Operating junction temperature range	-40	175	°C		
T _{JOP}	Recommended junction temperature under switching conditions	-40	T _{Jmax} -25			
T _{STG}	Storage Temperature Range	-40	125			
T _C	Operating Case Temperature	-40	125			
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight				110	g

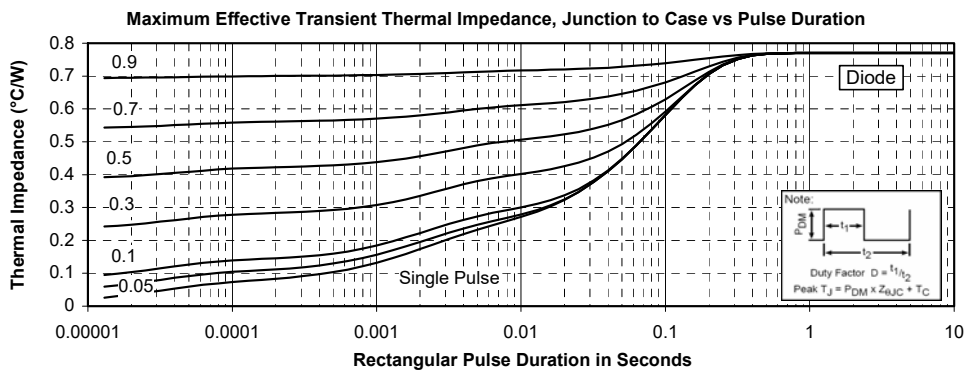
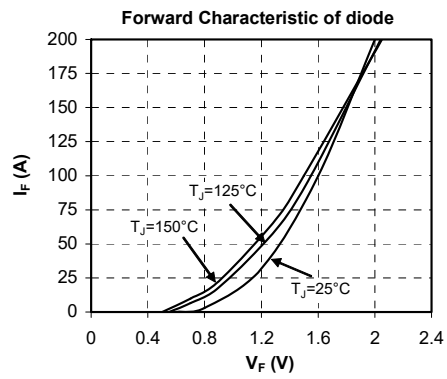
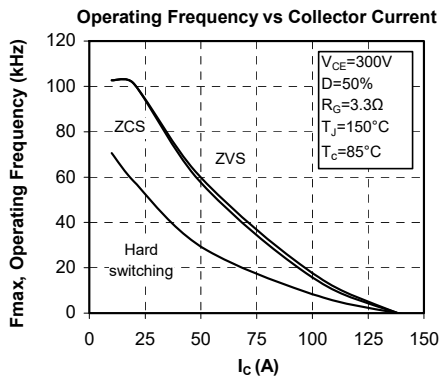
Package outline (dimensions in mm)



See application note 1906 - Mounting Instructions for SP3F Power Modules on www.microsemi.com

Typical Performance Curve





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